

## ABSTRACT

There is provided a copper foil with an improved surface which makes the laser processing easier and is suitable for forming an interlayer connection microhole in the production of printed circuit boards. Specifically, the copper foil is such that it is used in laser beam drilling, characterized in that at least the portion of the surface thereof which the laser beam enters is plated with at least one or more kinds of metals comprising copper, so as to form a particle layer 0.01 to 3  $\mu\text{m}$  thick thereon.